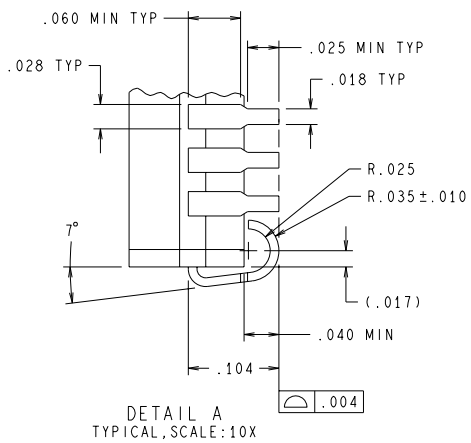
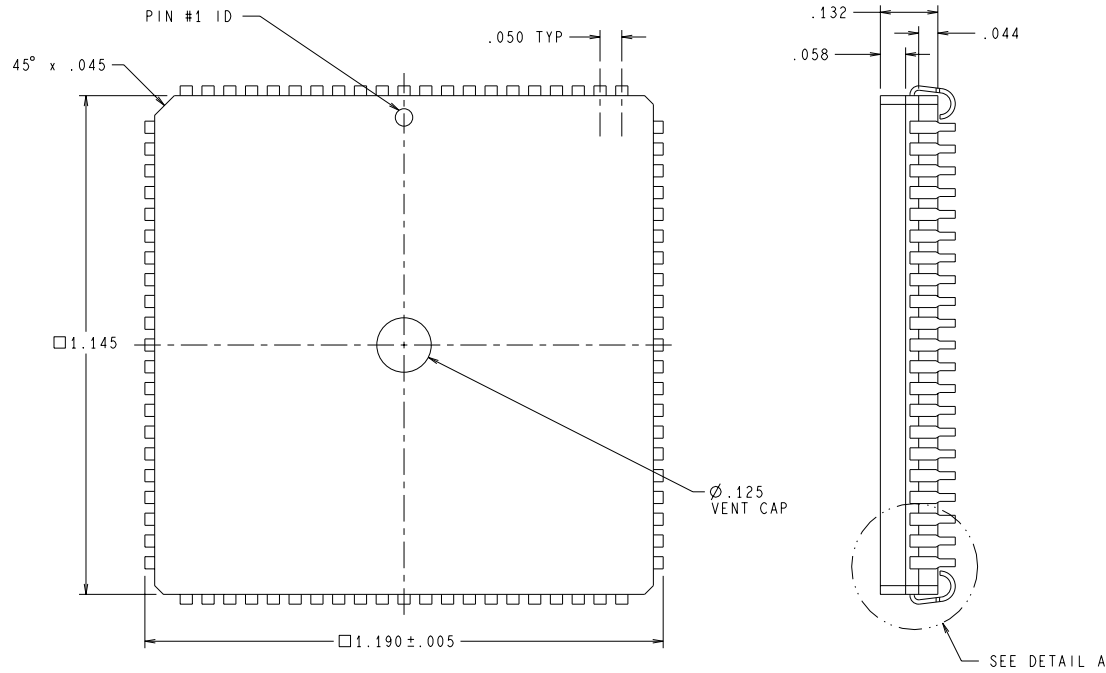


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10669	11/11/94	KES/



DIMENSIONS ARE IN INCHES

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- TOLERANCE OF LEAD FRAME TO PACKAGE BODY IS
±.020 MAXIMUM.
- REFERENCE INDY DRAWING 04-084-YO-001 REV B,
DATED 09/09/92.

APPROVALS		DATE		 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN KURT SINCERBOX		11/11/94					
DTG. CHK.							
ENGR. CHK.							
 INCH [MM]				SCALE	SIZE	DRAWING NUMBER	REV
				N/A	C	MKT-AA84A	A
DO NOT SCALE DRAWING						SHEET 1 of 1	

METAL LEADED CHIP
CARRIER, J-BEND, .050 LD
PITCH, 84 LD, CAVITY UP